PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kui-hyun KIM	01/24/2007
Byung-chul KIM	01/24/2007
Su-hyeon KIM	01/24/2007

RECEIVING PARTY DATA

Name:	Samsung Electronics Co., Ltd
Street Address:	416, Maetan-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11684393

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	YPL-0376
NAME OF SUBMITTER:	James J. Merrick

Total Attachments: 2
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ASSIGNMENT

WHEREAS We, **Kui-hyun KIM of c/o Samsung Advanced Institute of Technology, San 14-1 Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea; Byung-chul KIM of c/o Samsung Advanced Institute of Technology, San 14-1 Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea;** and **Su-hyeon KIM of c/o Samsung Advanced Institute of Technology, San 14-1 Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea;** (hereinafter referred to as "ASSIGNORS"); have invented certain new and useful improvements in:

APPARATUS AND METHOD FOR PRINTING BIOMOLECULAR DROPLET ON SUBSTRATE

which claims priority to Korean Application No. 10-2006-0033581, filed on April 13, 2006, and for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, **Samsung Electronics Co., Ltd.,** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Korea, having a place of business at **416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea,** is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 20070124 ______________________ L.S.
Kui-hyun KIM

Date: 20070124 ______________________ L.S.
Byung-chul KIM

Date: 20070124 ______________________ L.S.
Su-hyeon KIM